



BSS138

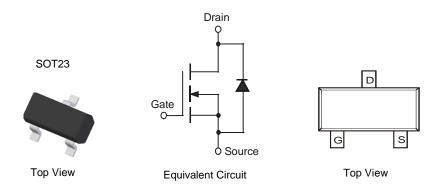
N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 @3
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)



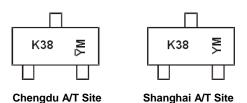
Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
BSS138-7-F	Commercial	SOT23	3000/Tape & Reel
BSS138-13-F	Commercial	SOT23	10000/Tape & Reel
BSS138Q-7-F	Automotive	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/product_compliance_definitions.html.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



K38 = Product Type Marking Code YM = Date Code Marking for SAT (Shanghai Assembly/ Test Site) \overline{Y} M = Date Code Marking for CAT (Chengdu Assembly/ Test Site) Y or \overline{Y} = Year (ex: E = 2017)

M = Month (ex: 9 = September)

Date Code Kev

Date Code Ney															
Year	1998	1999	2000		2002	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code	J	K	L		N	D	Е	F	G	Н	I	J	K	L	М
Month	Jan	Fe	b	Mar	Apr	May	Ju	n	Jul	Aug	Sep	Oc	t	Nov	Dec
Code	1	2		3	4	5	6	;	7	8	9	0		N	D



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	50	V
Drain-Gate Voltage $R_{GS} \le 20K\Omega$	V_{DGR}	50	V
Gate-Source Voltage Continuo	IS Vara	±20	V
Gate-Source Voltage Non Repetitive, Pulse Width<50	V _{GSS}	±40	V
Drain Current Continuo	ıs I _D	200	mA
Pulsed Drain Current (10µs Pulse Duty Cycle = 1%)	I _{DM}	1	A

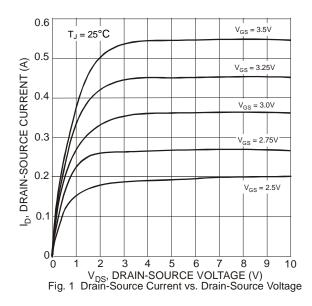
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

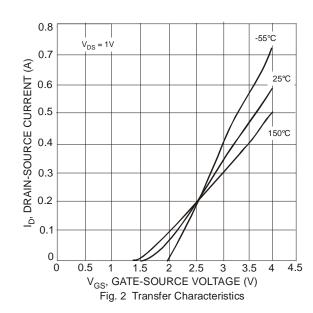
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	300	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 7)		•		•	•			
Drain-Source Breakdown Voltage	BV _{DSS}	50	75	_	V	$V_{GS} = 0V, I_D = 250\mu A$		
Zero Gate Voltage Drain Current	I _{DSS}	_		0.5	μΑ	$V_{DS} = 50V, V_{GS} = 0V$		
Gate-Body Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage	V _{GS(TH)}	0.5	1.2	1.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		
Static Drain-Source On-Resistance	R _{DS(ON)}		1.4	3.5	Ω	$V_{GS} = 10V, I_D = 0.22A$		
Forward Transconductance	g _{FS}	100	_	_	mS	$V_{DS} = 25V$, $I_D = 0.2A$, $f = 1.0KHz$		
DYNAMIC CHARACTERISTICS								
Input Capacitance	Ciss	_		50	pF			
Output Capacitance	Coss	_		25	pF	$V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz$		
Reverse Transfer Capacitance	C_{rss}	_	_	8.0	pF			
SWITCHING CHARACTERISTICS								
Turn-On Delay Time	t _{D(ON)}			20	ns	V 20V I 0.24 B 500		
Turn-Off Delay Time	t _{D(OFF)}	_		20	ns	$V_{DD} = 30V, I_D = 0.2A, R_{GEN} = 50\Omega$		

Notes:





^{6.} Device mounted on FR-4 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.7. Short duration pulse test used to minimize self-heating effect.



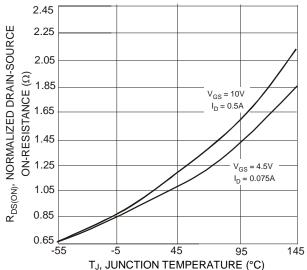


Fig. 3 Drain-Source On-Resistance vs. Junction Temperature

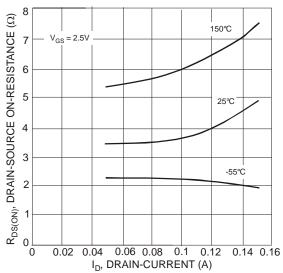


Fig. 5 Drain-Source On-Resistance vs. Drain-Current

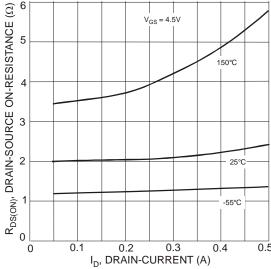
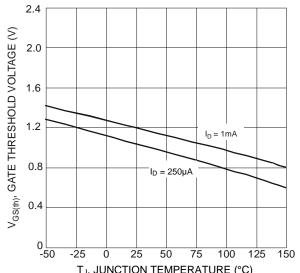


Fig. 7 Drain-Source On-Resistance vs. Drain-Current



T_J, JUNCTION TEMPERATURE (°C) Fig. 4 Gate Threshold Variation vs. Junction Temperature

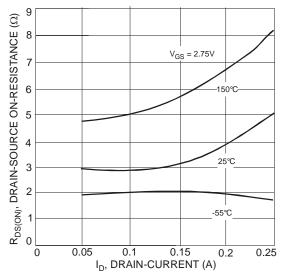


Fig. 6 Drain-Source On-Resistance vs. Drain-Current

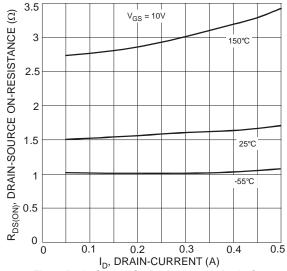
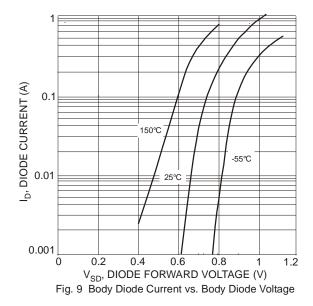
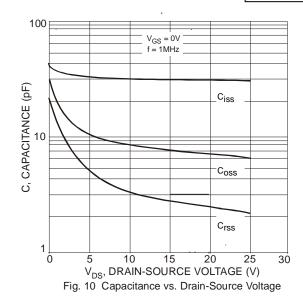


Fig. 8 Drain-Source On Resistance vs. Drain-Current

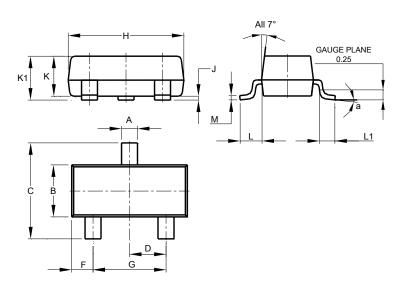






Package Outline Dimensions

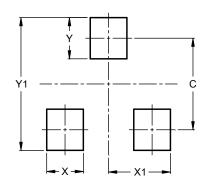
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
٦	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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